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Our File No.: SPLX.P0078

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Mani Adeli

10619  
10-23-03

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application for:

Steven Teig, et al.

Serial No.: 10/066,047

Filing Date: 1/31/02

For: NON-RECTILINEAR POLYGONAL  
VIAS

Examiner: <not assigned yet>

**PRELIMINARY AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

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MAY 29 2003  
TC 2800 MAIL ROOM

Please amend the application as follows:

**IN THE SPECIFICATION**

Please delete the "Claim of Benefit to Provisional Application" on page 1, lines 2-9, and insert therein a new "Claim of Benefit to Prior Applications" as follows:

**--CLAIM OF BENEFIT TO PROVISIONAL APPLICATION**

Q1  
This patent application claims the benefit of the earlier-field U.S. Provisional Patent Application entitled "Interconnect Method, Apparatus, and Architecture for Integrated Circuits and Integrated-Circuit Layouts", having serial number 60/295,735, and filed 6/3/2001; and U.S. Provisional Patent Application entitled "Interconnect Method, Apparatus, and Architecture for Integrated Circuits and Integrated-Circuit Layouts", having serial number 60/298,146, and filed